**PATENT** 10/612,281

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Brian Taggart et al.

Examiner: Jeremy Norris

al No.:

10/612,281

Group Art Unit: 2841

June 30, 2003

Docket No.: 884.853US1

Title:

BOND FINGER ON VIA SUBSTRATE, PROCESS OF MAKING SAME,

PACKAGE MADE THEREBY, AND METHOD OF ASSEMBLING SAME

Assignee:

Intel Corporation

Customer No: 21186

## AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## PRELIMINARY REMARKS

Applicant acknowledges Examiner Norris' graciously granting an interview, held on February 7, 2005 with Applicant's representative, John Greaves.

This responds to the Office Action mailed on December 28, 2004. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from March 28, 2005 to April 28, 2005.

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